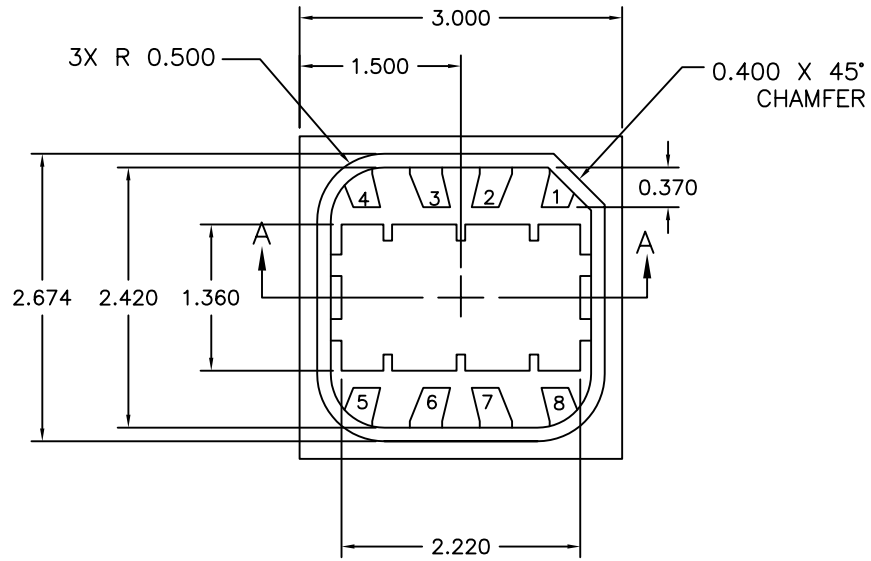
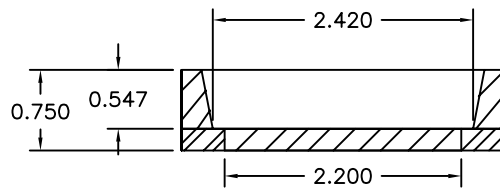


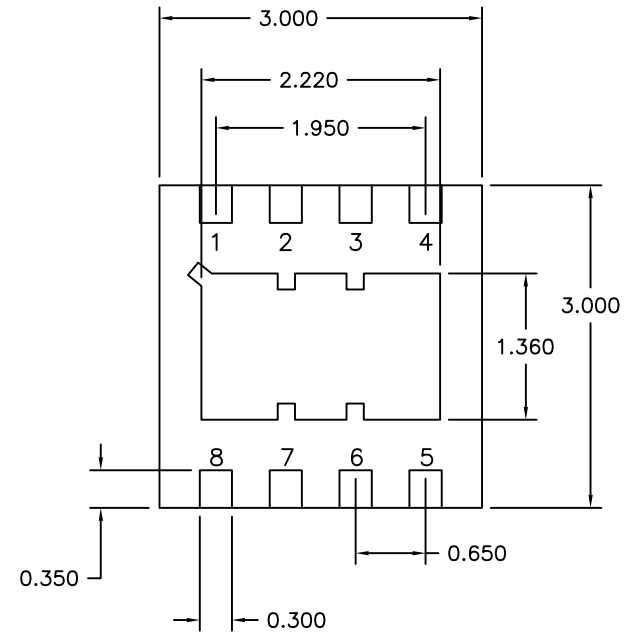
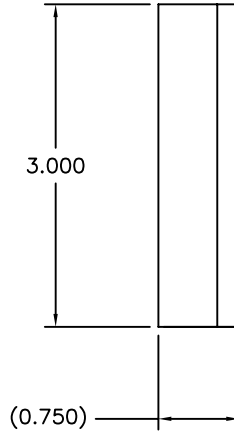
SEMPAK REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10963	09/16/08	PRODUCTION RELEASE	D.MORRIS



TOP VIEW



SECTION A-A



BOTTOM VIEW

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
  3. LEAD FRAME: COPPER, 194 FH.
  4. LEAD FINISH: FULL GOLD PLATE.
  5. FRAME THICKNESS: 0.2030 ± 0.0076.
  6. DIE PAD: 1.360mm X 2.200mm.
  7. JEDEC OUTLINE REFERENCE: MO-229 (VEEC-1,2)

	THIRD ANGLE PROJECTION
	UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE: X.XX ± 0.015 X.XXXX ± --- X.XXX ± 0.050 ANGLES: ± 1°

DRAWN BY	VSK	DATE	09/16/08
APP BY	P. FLASKERUD	DATE	09/16/08
CUSTOMER	---		
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<b>SEMPAC, INC.</b> <b>Open-Pak™ Technologies</b> <a href="http://www.sempac.com">www.sempac.com</a> 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006			
8 LEAD 3mm X 3mm DFN Open-Pak™			
SIZE	PART NO.	REV	
A	DFN3X3-08-OP-01	1	
SCALE	CAD FILE	SHEET 1 OF 1	
NONE	DFN3X3-08-OP-01-R1.DWG		